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FDC6318P

Dual P-Channel 1.8V PowerTrench® Specified MOSFET

General Description

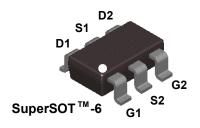
These P-Channel 1.8V specified MOSFETs are produced using Fairchild Semiconductor's advanced PowerTrench process that has been especially tailored to minimize on-state resistance and yet maintain low gate charge for superior switching performance.

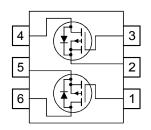
Applications

- Power management
- Load switch

Features

- -2.5 A, -12 V. $R_{DS(ON)} = 90 \text{ m}\Omega$ @ $V_{GS} = -4.5 \text{ V}$ $R_{DS(ON)} = 125 \text{ m}\Omega$ @ $V_{GS} = -2.5 \text{ V}$ $R_{DS(ON)} = 200 \text{ m}\Omega$ @ $V_{GS} = -1.8 \text{ V}$
- • High performance trench technology for extremely low $R_{\mbox{\tiny DS(ON)}}$
- SuperSOTTM-6 package: small footprint (72% smaller than standard SO-8); low profile (1mm thick)





Absolute Maximum Ratings T_A=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		-12	V
V _{GSS}	Gate-Source Voltage		±8	V
I_D	Drain Current - Continuous	(Note 1a)	-2.5	Α
	- Pulsed		-7	
P _D	Power Dissipation for Single Operation	(Note 1a)	0.96	W
		(Note 1b)	0.9	
		(Note 1c)	0.7	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	130	°C/W
R _{eJC}	Thermal Resistance, Junction-to-Case	(Note 1)	60	°C/W

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
.318	FDC6318P	13"	12mm	3000 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Char	acteristics				ı	
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = -250 \mu\text{A}$	-12			V
<u>ΔBV_{DSS}</u> ΔT _J	Breakdown Voltage Temperature Coefficient	I_D = -250 μ A, Referenced to 25°C		-2.9		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}$			-1	μΑ
I _{GSSF}	Gate–Body Leakage, Forward	V _{GS} = 8 V, V _{DS} = 0 V			100	nA
I _{GSSR}	Gate-Body Leakage, Reverse	$V_{GS} = -8 \text{ V}, \qquad V_{DS} = 0 \text{ V}$			-100	nA
On Char	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \mu\text{A}$	-0.4	-0.7	-1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	I_D = –250 μA, Referenced to 25°C		2.3		mV/°C
$R_{DS(on)}$	Static Drain–Source On–Resistance	$\begin{split} V_{GS} &= -4.5 \text{ V}, I_D = -2.5 \text{ A} \\ V_{GS} &= -2.5 \text{ V}, I_D = -2 \text{ A} \\ V_{GS} &= -1.8 \text{ V}, I_D = -1.6 \text{ A} \\ V_{GS} &= -4.5 \text{ V}, I_D = -2.5 \text{A}, T_J = 125 ^{\circ}\text{C} \end{split}$		69 93 135 85	90 125 200 120	mΩ
I _{D(on)}	On-State Drain Current	$V_{GS} = -4.5 \text{ V}, V_{DS} = -5 \text{ V}$	-6			Α
g _{FS}	Forward Transconductance	$V_{DS} = -5 \text{ V}, \qquad I_{D} = -2.5 \text{ A}$		8		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = -6 \text{ V}, V_{GS} = 0 \text{ V},$		455		pF
Coss	Output Capacitance	f = 1.0 MHz		194		pF
C _{rss}	Reverse Transfer Capacitance	7		134		pF
Switchir	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = -6 \text{ V}, I_{D} = -1 \text{ A},$		9	18	ns
t _r	Turn-On Rise Time	$V_{GS} = -4.5 \text{ V}, R_{GEN} = 6 \Omega$		14	25	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time	7		21	34	ns
t _f	Turn-Off Fall Time	7		17	31	ns
Qg	Total Gate Charge	$V_{DS} = -6 \text{ V}, \qquad I_{D} = -2.5 \text{ A},$		5.4	8	nC
Q _{gs}	Gate-Source Charge	V _{GS} = -4.5 V		1.1		nC
Q_{gd}	Gate-Drain Charge	1		1.3		nC
Drain-S	ource Diode Characteristics	and Maximum Ratings				
Is	Maximum Continuous Drain–Source				-0.8	Α
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, \qquad I_S = -0.8 \text{ A} \text{(Note 2)}$		-0.7	-1.2	V

Notes

 R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0JC} is guaranteed by design while R_{0CA} is determined by the user's board design.



 a) 130 °C/W when mounted on a 0.125 in² pad of 2 oz. copper.



b) 140°C/W when mounted on a .004 in² pad of 2 oz copper



c) 180°C/W when mounted on a minimum pad.

Scale 1:1 on letter size paper

2. Pulse Test: Pulse Width < 300µs, Duty Cycle < 2.0%

Typical Characteristics

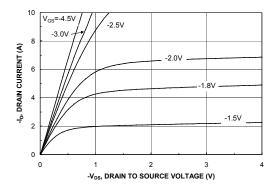


Figure 1. On-Region Characteristics.

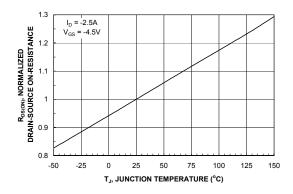


Figure 3. On-Resistance Variation with Temperature.

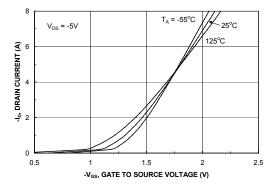


Figure 5. Transfer Characteristics.

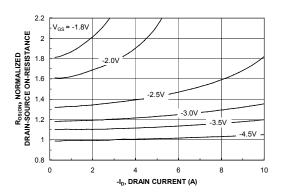


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage.

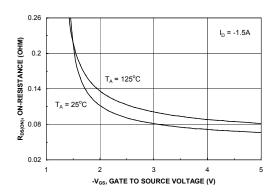


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

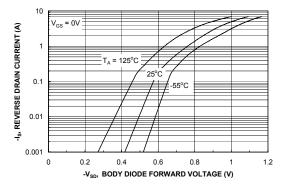
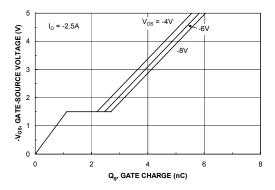


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



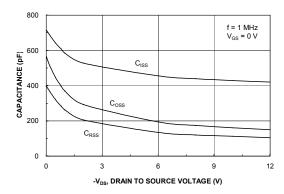
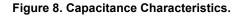
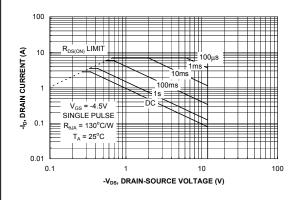


Figure 7. Gate Charge Characteristics.





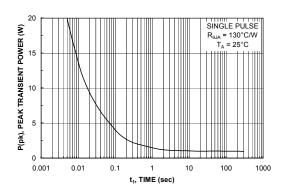


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

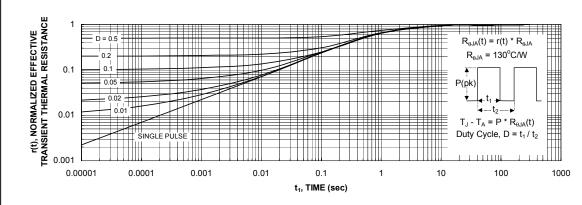


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.

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